

Notice of References Cited		Application/Control Number 09/763,891	Applicant(s)/Patent Under Reexamination UCHIDA ET AL.	
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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	C	US-5434107	07-1995	Paranjepe	437/225
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*	E	US-5770095	06-1998	Sasaki et al.	216/38
*	F	US-5770103	06-1998	Wang et al.	252/79.1
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*	H	US-5932486	08-1999	Cook et al.	438/692
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NON-PATENT DOCUMENTS

*	Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages	
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.